

**IN THE SPECIFICATION:**

Please enter the below changes to the specification in the record.

At page 1, between lines 3 and 4, please insert the following:

**BACKGROUND OF THE INVENTION**

1. **Field of the Invention**

At page 1, between lines 6 and 7, please insert the following

2. **Discussion of Background Information**

At page 1, between lines 30 and 31 , please insert the following:

**SUMMARY OF THE INVENTION**

At page 1, please replace the paragraph at lines 31-36 as follows:

~~One object of the The invention is thus to specify~~ specifies an arrangement by ~~means~~ of which the packing density of surface mounted devices on a printed circuit can be increased while taking into account a simple design and short signal paths.

Please replace the paragraph spanning pages 1 and 2 as follows:

This ~~object~~ is achieved by the arrangement as claimed in patent claim 1. Advantageous embodiments of the invention are the subject matter of dependent claims.

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At page 2, please replace the paragraph at lines 22-24 as follows:

The via holes are holes and may in particular be microvias, and may be produced by ~~means of~~ drilling, electroplating or etching processes.

At page 3, between lines 13 and 14, please insert the following:

BRIEF DESCRIPTION OF THE DRAWINGS

At page 3, between lines 35 and 36, please insert the following:

DETAILED DESCRIPTION OF THE PRESENT INVENTION